Abstracts

LTCC as MCM substrate: design of strip-line structures and flip-chip interconnects

F.J. Schmuckle, A. Jentzsch, W. Heinrich, J. Butz and M. Spinnler. "LTCC as MCM substrate: design of strip-line structures and flip-chip interconnects." 2001 MTT-S International Microwave Symposium Digest 01.3 (2001 Vol. III [MWSYM]): 1903-1906 vol.3.

LTCC multilayer substrates offer a cost-effective MCM solution for frequencies around 20 GHz and beyond. This paper reports on LTCC-specific transmission-line structures using a commercially available process. For the chip interconnect, a flip-chip approach contacting the backside is chosen, which, in a first step, is realized on conventional ceramics.

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